



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
 [List multiple models if applicable.]

HP Compaq 8080 Elite Convertible Minitower PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

- 1.1 Items listed below are classified as requiring selective treatment.
- 1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

| Item Description | Notes | Quantity of items included in product |
|--|---|---------------------------------------|
| Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) | With a surface greater than 10 sq cm | 2 |
| Batteries | All types including standard alkaline and lithium coin or button style batteries | 1 |
| Mercury-containing components | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm | Includes background illuminated displays with gas discharge lamps | |
| Cathode Ray Tubes (CRT) | | |
| Capacitors / condensers (Containing PCB/PCT) | | |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height | | 1 |
| External electrical cables and cords | | |
| Gas Discharge Lamps | | |
| Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above) | system fan, psu fan, heatsink fan | 3 |
| Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | |
| Components and waste containing asbestos | | |

| | | |
|--|--|--|
| Components, parts and materials containing refractory ceramic fibers | | |
| Components, parts and materials containing radioactive substances | | |

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

| Tool Description | Tool Size (if applicable) |
|------------------|---------------------------|
| Screwdriver | T-15 |
| Micro shear | 170II |
| Screwdriver | PH1 |
| Description #4 | |
| Description #5 | |

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the access panel.(see Figure 1 below)
2. Disconnect the cables from the board.(see Figure 2-5 below)
3. Remove the HDD from cage.(see Figure 6 below)
4. Remove PSU from chassis.(see Figure 7&8 below)
5. Remove system fan.(see Figure 9&10 below)
6. Remove the Memory card from the board.(see Figure 11 below)
7. Remove the CPU from the board .(see Figure 12-14 below)
8. Remove the battery from the system board.(see Figure 15 below)
9. Remove M/B from chassis.(see Figure 16&17 below)
10. Remove front panel.(see Figure 18 below)
11. Remove ODD from chassis.(see Figure 19 below)
12. Remove PSU cover.(see Figure 20&21 below)
13. Disconnect all the cables and remove the Electrolytic Capacitors.(see Figure 22-26 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Figure 1 Remove the side panel:



Figure 2 Disconnect the cables from the board



Figure 3 Disconnect PSU cables from the board



Figure 4 Disconnect the cables from the ODD



Figure 5 Disconnect the cables from the HDD



Figure 6 Remove the HDD from cage



Figure 7 Loose the screws from PSU



Figure 8 Press the baffle and slide the PSU



Figure 9 Loose the screws from system fan



Figure 10 Remove system fan



Figure 11 Remove the Memory card from the board



Figure 12 Loose the screws and remove CPU fan



Figure 13 Rotate the handle and open it up



Figure 14 Remove the CPU from the board

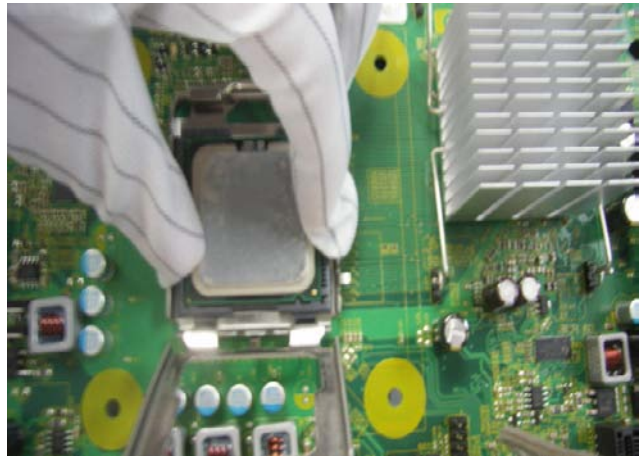


Figure 15 Remove the battery from the system board



Figure 16 Loose the screws from board



Figure 17 Remove M/B from chassis



Figure 18 Remove front panel



Figure19 Remove ODD from chassis



Figure 20 Remove the screws on the PSU chassis

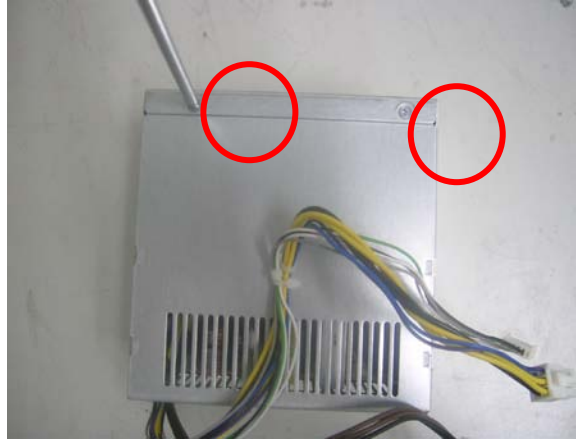


Figure 21 Lift the cover off the power supply



Figure 22 Remove the four screws on the board

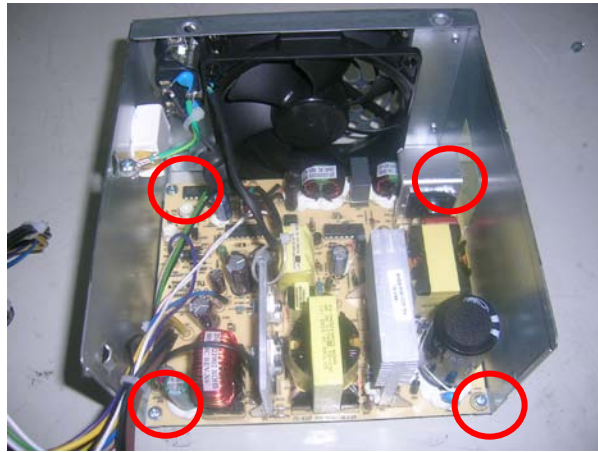


Figure 23 Using Soldering Iron, heat the solder of the cables which connect to the PCA, then remove them

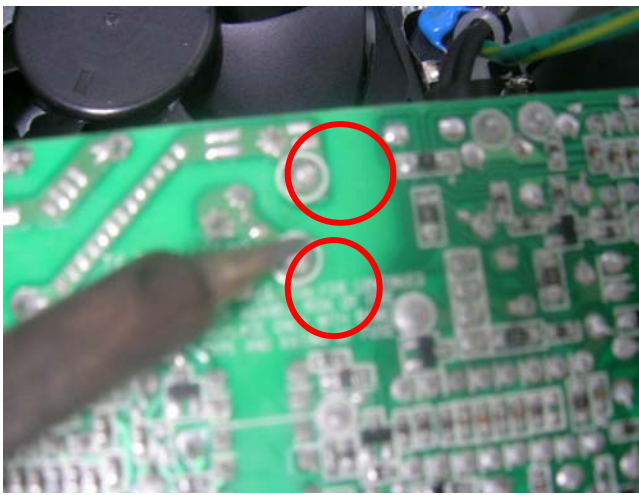


Figure 24 Remove the power supply PCA from the power supply chassis



Figure 25 Heat the solder of Electrolytic Capacitors

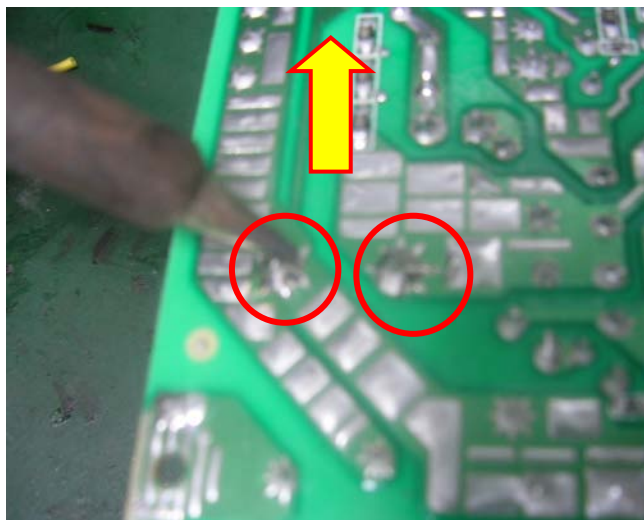


Figure 26 Remove the Electrolytic Capacitors

